

Thermal Testing

ATS tests to all 11 current JEDEC 51 standards, which cover various environmental and test board conditions for common package types such as wire bond chips, leaded surface mount components, and perimeter and area array through-hole leaded packages. Chipmakers and board manufacturers complying with JEDEC 51 test standards can use and pass along important junction temperature values for wide-ranging applications and a variety of package designs.

• Fewer parts need to be tested

• Effective cooling solutions more easily found

• Test results can be duplicated and relied upon

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http://www.mdtmag.com/product-releases/2004/12/thermal-testing?qt-most_popular=0&qt-recent_content=0